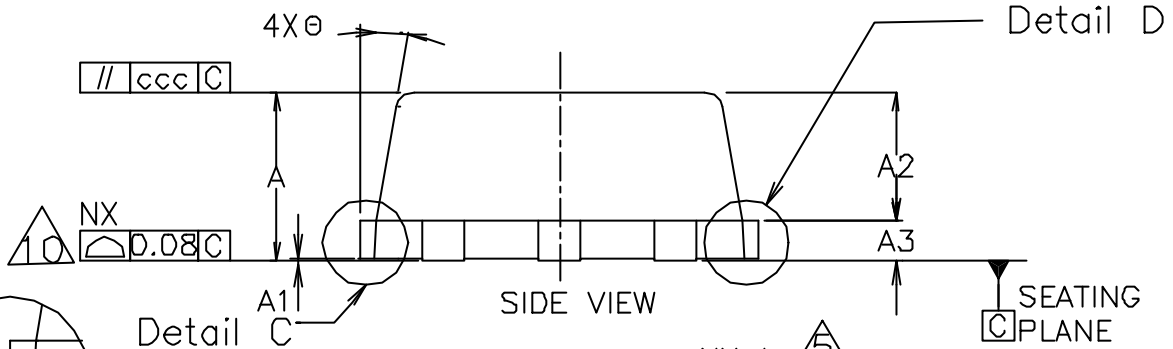
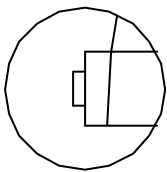


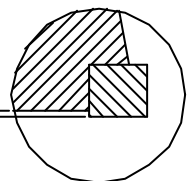
TOP VIEW



SIDE VIEW



Detail C

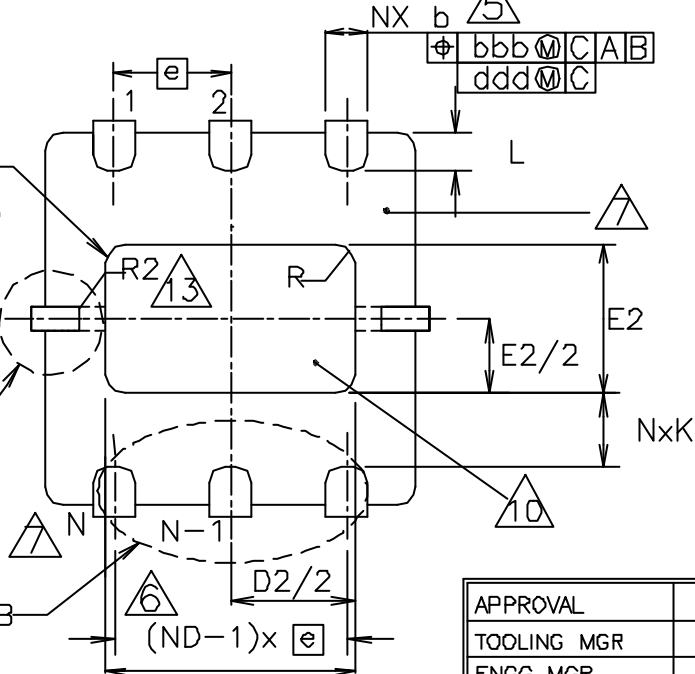


Detail D

Exposed pad (Optional)

SEE DETAIL A

SEE DETAIL B



D2
BOTTOM VIEW

APPROVAL	SIGN	DATE
TOOLING MGR		
ENGG MGR		
OPERATIONS MGR		

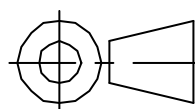
FIGURE 1

FOR REVISION UPDATE PLEASE REFER TO HISTORY OF CHANGES.

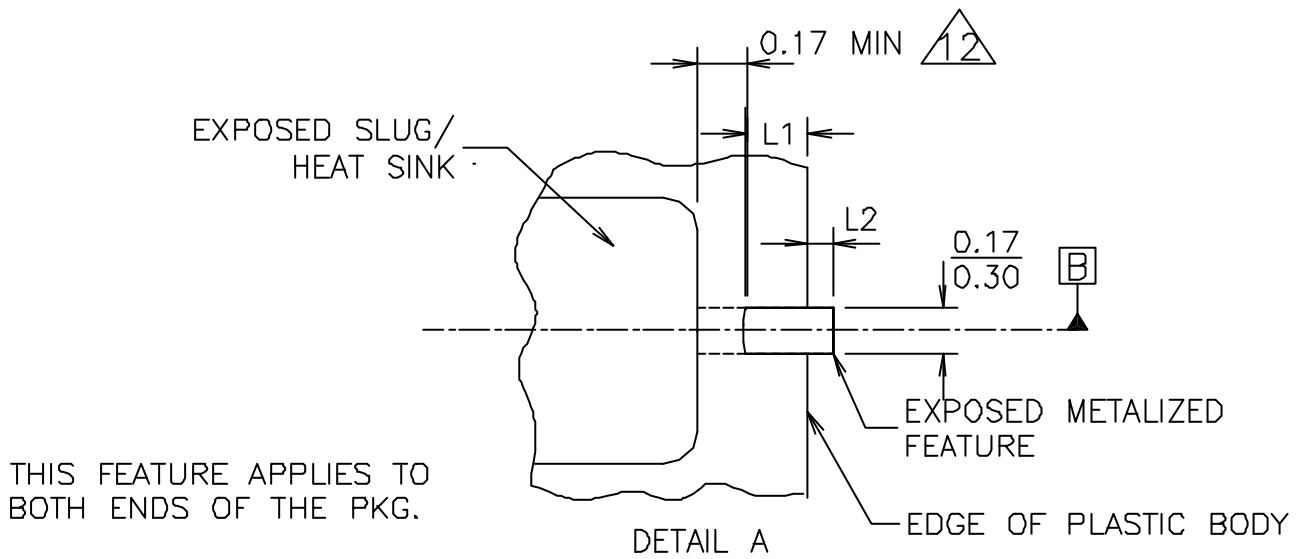
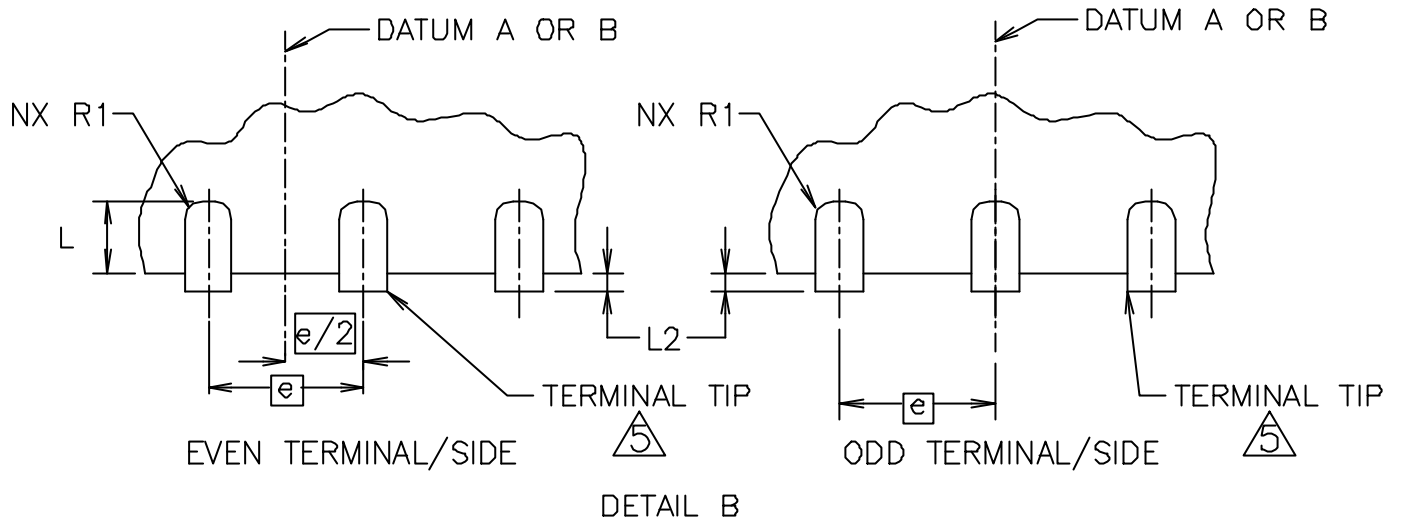
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REV
C


DWG NO:	MLPM-CPOD-0001
APP'D	-
CHECKED	CC YIP
DESIGNED	-
DRAWN	KC LAU



FILE:- MLPM-CPOD-0001-RevC
MLP MICRO PACKAGE OUTLINE (ISOLATED EXPOSED PAD & COL)
PAGE 1 of 9



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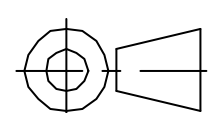
REV C	DWG NO: - MLPM-CPOD-0001			FILE:- MLPM-CPOD-0001-RevC
	APP'D	-		MLP MICRO
	CHECKED	CC YIP		PACKAGE OUTLINE
	DESIGNED	-		(ISOLATED) EXPOSED PAD & COL
	DRAWN	KC LAU		PAGE 1 2 of 9

TABLE 1




VARIATION DESIGNATORS							
FIRST DIGIT CODE		SECOND DIGIT CODE		THIRD DIGIT CODE		FOURTH DIGIT CODE	
OVERALL HEIGHT		BODY LENGTH		BODY WIDTH		TERMINAL PITCH	
A	LETTER CODE	D	LETTER CODE	E	LETTER CODE	e	LETTER CODE
1.0 MAX	V	1.0	A	1.0	A	0.95	A
		1.5	B	1.5	B	0.65	C
		2.0	C	2.0	C	0.50	D
		2.5	D	2.5	D		
		3.0	E	3.0	E		

TABLE 2: TOLERANCE OF FORM AND POSITION

PITCH (MM) / SYMBOL	0.95	0.65	0.50
aaa	0.10	0.10	0.10
bbb	0.10	0.10	0.10
ccc	0.10	0.10	0.10
ddd	0.05	0.05	0.05
NOTES	1,2		
REF			
ISSUE			

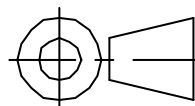


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DWG NO:	MLPM-CPOD-0001
APP'D	-
CHECKED	CC YIP
DESIGNED	-
DRAWN	KC LAU



FILE:- MLPM-CPOD-0001-RevC
MLP MICRO PACKAGE OUTLINE (ISOLATED) EXPOSED PAD & COL
PAGE : 3 of 9

TABLE 3: COMMON HEIGHT DIMENSION


V-PROFILE HEIGHT

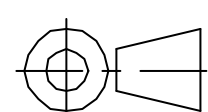
DIM SYMBOL	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0	0.025	0.05
A2	0.65	0.70	0.75
A3	0.15	0.20	0.25
θ	0°	10°	12°
NOTES	1,2		
REF			
ISSUE			

TABLE 4: COMMON TERMINAL DIMENSIONS

DIM PITCH	L2 MAX	K MIN
0.95	0.125	0.20
0.65	0.125	0.20
0.50	0.125	0.20
NOTES	5,11	5,11
REF		
ISSUE		

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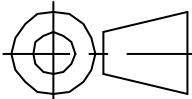
REV C	DWG NO: - MLPM-CPOD-0001		FILE:- MLPM-CPOD-0001-RevC
	APP'D -		MLP MICRO PACKAGE OUTLINE (ISOLATED EXPOSED PAD & COL)
	CHECKED CC YIP		PAGE 4 of 9
	DESIGNED -		
	DRAWN KC LAU		

△ SUMMARY TABLE 5

BODY SIZE (mm)	LEAD PITCH (mm)	LEAD COUNT	VERY THIN PROFILE
2.00 X 2.00	0.65	6	VCCC-C
2.00 X 2.00	0.50	8	VCCD-3E
3.00 X 2.00	0.95	6	VECA-C
3.00 X 2.00	0.65	8	VECC-E
3.00 X 2.00	0.50	10	VECD-3E
3.00 X 3.00	0.95	6	VEEA-E
3.00 X 3.00	0.95	6	VEEA-C
3.00 X 3.00	0.65	8	VEEC-E
3.00 X 3.00	0.65	8	VEEC-C
3.00 X 3.00	0.50	10	VEED-3C
3.00 X 3.00	0.50	10	VEED-3E

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REV C	DWG NO: - MLPM-CPOD-0001			FILE:- MLPM-CPOD-0001-RevC
	APP'D	-		MLP MICRO
	CHECKED	CC YIP		PACKAGE OUTLINE
	DESIGNED	-		(ISOLATED) EXPOSED PAD & COL)
	DRAWN	KC LAU		PAGE 1 5 of 9

SUMMARY TABLE 5 0.50mm PITCH VARIATION

SYMBOL						NOTE
b MIN	0.18	0.18	0.18	0.18	0.18	
b NOM	0.20	0.20	0.20	0.20	0.20	
b MAX	0.28	0.28	0.28	0.28	0.28	
D BSC	2.00	2.00	3.00	3.00	3.00	
D2 MIN	-	0.92	1.82	1.92	-	
D2 NOM	-	1.02	1.92	2.02	-	
D2 MAX	-	1.12	2.02	2.12	-	
E BSC	2.00	2.00	2.00	3.00	3.00	
E2 MIN	-	0.46	0.41	1.11	-	
E2 NOM	-	0.56	0.51	1.21	-	
E2 MAX	-	0.66	0.61	1.31	-	
L MIN	0.20	0.20	0.20	0.20	0.20	
L NOM	0.29	0.29	0.29	0.29	0.29	
L MAX	0.45	0.45	0.45	0.45	0.45	
L1 MIN	0.20	0.20	0.20	-	0.20	
L1 NOM	0.29	0.29	0.29	-	0.29	
L1 MAX	0.45	0.45	0.45	-	0.45	
N	6	8	10	10	10	3
ND	3	4	5	5	5	6
R REF	-	0.075	0.075	0.15	-	
R1 REF	0.075	0.075	0.075	0.075	0.075	
R2 REF	0.075	0.075	0.075	-	0.075	
VARV	VCC-C	VCCD-3E	VECD-3E	VEED-3E	VEED-3C	
NOTE	1,2,9	1,2,9	1,2,9	1,2,9	1,2,9	
REF						
ISSUE						

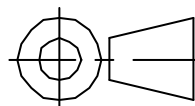
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REV
C

DWG NO: - MLPM-CPOD-0001

APP'D	-
CHECKED	CC YIP
DESIGNED	-
DRAWN	KC LAU




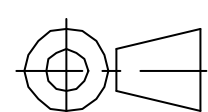
FILE:- MLPM-CPOD-0001-RevC
MLP MICRO PACKAGE OUTLINE
(ISOLATED) EXPOSED PAD & COL
PAGE : 6 of 9

SUMMARY TABLE 6 0.65mm PITCH VARIATION

SYMBOL				NOTE
b MIN	0.24	0.285	0.285	
b NOM	0.26	0.305	0.305	
b MAX	0.34	0.385	0.385	
D BSC	3.00	3.00	3.00	
D2 MIN	1.82	1.92	-	
D2 NOM	1.92	2.02	-	
D2 MAX	2.02	2.12	-	
E BSC	2.00	3.00	3.00	
E2 MIN	0.41	1.11	-	
E2 NOM	0.51	1.21	-	
E2 MAX	0.61	1.31	-	
L MIN	0.20	0.20	0.20	
L NOM	0.29	0.29	0.29	
L MAX	0.45	0.45	0.45	
L1 MIN	0.20	0.16	0.20	
L1 NOM	0.29	0.24	0.29	
L1 MAX	0.45	0.40	0.45	
N	8	8	8	3
ND	4	4	4	6
R REF	0.075	0.15	-	
R1 REF	0.075	0.15	0.15	
R2 REF	0.075	-	0.15	
VARV	VECC-E	VEEC-E	VEEC-C	
NOTE	1,2,9	1,2,9	1,2,9	
REF				
ISSUE				

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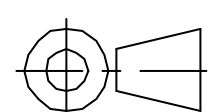
REV C	DWG NO: - MLPM-CPOD-0001		FILE:- MLPM-CPOD-0001-RevC
	APP'D -		MLP MICRO
	CHECKED CC YIP		PACKAGE OUTLINE
	DESIGNED -		(ISOLATED) EXPOSED PAD & COL
	DRAWN KC LAU		PAGE : 7 of 9

SUMMARY TABLE 7 0.95mm PITCH VARIATION

SYMBOL										NOTE
b MIN	0.33	0.33	0.33							
b NOM	0.35	0.35	0.35							
b MAX	0.43	0.43	0.43							
D BSC	3.00	3.00	3.00							
D2 MIN	-	1.92	-							
D2 NOM	-	2.02	-							
D2 MAX	-	2.12	-							
E BSC	2.00	3.00	3.00							
E2 MIN	-	1.11	-							
E2 NOM	-	1.21	-							
E2 MAX	-	1.31	-							
L MIN	0.20	0.20	0.20							
L NOM	0.29	0.29	0.29							
L MAX	0.45	0.45	0.45							
L1 MIN	0.20	0.16	0.20							
L1 NOM	0.29	0.24	0.29							
L1 MAX	0.45	0.40	0.45							
N	6	6	6							3
ND	3	3	3							6
R REF	-	0.15	-							
R1 REF	0.127	0.127	0.127							
R2 REF	0.127	-	0.127							
VARV	VECA-C	VEEA-E	VEEA-C							
NOTE	1,2,9	1,2,9	1,2,9							
REF										
ISSUE										

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REV C	DWG NO: - MLPM-CPOD-0001			FILE:- MLPM-CPOD-0001-RevC
	APP'D	-		MLP MICRO
	CHECKED	CC YIP		PACKAGE OUTLINE
	DESIGNED	-		(ISOLATED EXPOSED PAD & COL)
	DRAWN	KC LAU		PAGE 18 of 9

Note:

1. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
2. All dimensions are in millimeters . All angles are in degrees.
3. N is the total number of terminals.

△4. The terminal #1 identifier and terminal numbering convention shall conform to JESD 95-1 SPP-012. Details of terminal #1 identifier are optional , but must be located within the zone indicated. The terminal #1 identifier may be a molded, marked, or metalized features.

△5. Dimension b applies to metalized terminal and is measured between 0.15 and 0.20mm from terminal tip.

△6. ND refer to the maximum number of terminals on D side.

7. Depopulation of terminals is allowed and will be called out on the individual variation.

△8. Variation VEEA is shown for illustration only.

△9. For a complete set of dimensions for each variation, see the individual variation and the common dimensions and tolerances on page 4 & 5.

△10. Coplanarity applies to the exposed heat sink slug as well as the terminals.

△11. Profile tolerance (aaa) will be applicable only to the plastic body, and not to the metalized features (such as the terminal tips and tie bars.) Metalized features may protrude a maximum of L2 from the plastic body profile.

△12. If L1 max is not called out, the metalized feature will extend to the exposed pad. Thus, the 0.17mm gap does not apply.

△13. Corner will be sharp unless otherwise specified with radius dimensions.

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REV
C

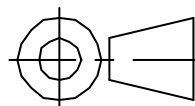
DWG NO: - MLPM-CPOD-0001

APP'D -

CHECKED CC YIP

DESIGNED -

DRAWN KC LAU



FILE:- MLPM-CPOD-0001-RevC

MLP MICRO
PACKAGE OUTLINE
(ISOLATED EXPOSED PAD & COL)

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